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National Phase Entry of PCT/JP03/08194  
Confirmation No.:  
Date:

APPLICATION DATA SHEET**Applicant Information**

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#### **Correspondence Information**

Correspondence Customer Number:: 06449

#### **Application Information**

Title Line One:: Method of forming dielectric filler-  
Title Line Two:: containing polyimide coating on metallic  
Title Line Three:: material, method of manufacturing copper  
Title Line Four:: clad laminate for forming capacitor layer  
Title Line Five:: for use in printed wiring board, and  
Title Line Six:: copper clad laminate obtained through the  
Title Line Seven:: manufacturing method  
Total Drawing Sheets:: 3  
Formal Drawings?:: Yes  
Application Type:: Utility  
Docket Number:: 2922-482

Secrecy Order in Parent Appl?:: No

#### **Representative Information**

Representative Customer Number:: The practitioners associated  
Representative Customer Number:: with customer number 06449

**Domestic Priority Information**

This application is a:: 371  
>Application One:: PCT/JP03/08194  
Filing Date:: June 27, 2003  
Patent Number::

**Foreign Priority Information**

Foreign Application One:: 2002-191517  
Filing Date:: June 28, 2002  
Country:: Japan  
Priority Claimed:: Yes

**Assignment Information**

Assignee name:: Mitsui Mining & Smelting Co., Ltd.  
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